CALENDAR

Upcoming: April 16–20 MRS Spring Meeting, MRS; June 5–8 E-MRS Spring Meeting, E-MRS; June 24–27 2001 International Workshop on Superconductivity (ISTEC), MRS.

To list an event in the Calendar, contact J. Meiksin, Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3004 ext. 522; fax 724-779-8313.

MRS, A-MRS, C-MRS, E-MRS, MRS-A, MRS-I, MRS-J, MRS-K, MRS-R, MRS-S, MRS-T, M-MRS, or IUMRS at the end of an entry indicates sponsorship or co-sponsorship of an event by the International Union of Materials Research Societies or one of its adhering bodies. "Endorsed" identifies events endorsed by MRS.

▼ identifies a new or revised entry this month.

See the January 2001 MRS BULLETIN for March 2001 Calendar entries.

APRIL 2001

1–5 ▼ 21st American Chemical Society Natl. Meeting, *San Diego, CA.* Dept. of Meetings, American Chemical Society, 1155-16th St., NW, Washington, DC 20036; 202-872-4396; fax 202-872-6128; e-mail natlmtgs@acs.org.

2–4 Intl. Sherwood Fusion Theory Conf., *Santa Fe, NM.* C. Sovinec, Los Alamos Natl. Lab., T-15, MS K717, Los Alamos, NM 87545; 505-667-4394; fax 505-665-7150; e-mail sovinec@lanl.gov; http://t15web.lanl.gove/sherwood2001/.

10–11 Northeast Regional Meeting on Optoelectronics, Photonics, and Imaging, *Rochester, NY.* A. Mitchell, SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail alexm@spie.org; www.spie.org.

10–13 23rd Intl. High Technology Safety, Industrial Hygiene and Environmental Symposium, *New Orleans, LA.* Semiconductor Safety Association, 1313 Dolley Madison Blvd., Ste. 402, McLean, VA 22101; 703-790-1745; fax 703-790-2672; e-mail SSA@BurkInc.com; www.semiconductorsafety.org.

16–20 **MRS Spring Meeting,** *San Francisco, CA.* Materials Research Society, 506 Keystone Dr., Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail info@mrs.org www.mrs.org. **MRS.**

18–20 Intl. Conf. on Electronics Packaging, and 15th Microelectronics Show, *Tokyo, Japan.* Secretariat, 2001 ICEP, JIEP, 3-12-2 Nishiogikita, Suginamu-ku, Tokyo 167-0042, Japan; 81-3-5310-2010; fax 81-3-5310-2011; e-mail imaps-j@jiep.or.jp; www.jiep.or.jp/index.html.

18–20 Intl. Conf. on High Density Interconnect and Systems Packaging, *Santa Clara, CA.* J. Morris, Conf. Coordinator, Intl. Microelectronics and Packaging Society, 1850 Centennial Park Dr., Ste. 105, Reston, VA 20191-1517; 888-464-6277; fax 703-758-1066; e-mail jmorris@imaps.org; www.imaps.org.

20–21 IMAPS Advanced Technology Workshop on Thermal Management for High-Performance Computing and Applications, *Palo Alto, CA.* Intl. Microelectronics and Packaging Society, 1850 Centennial Park Dr., Ste. 105, Reston, VA 20191-1517; 888-464-6277; fax 703-758-1066; e-mail dsaums@msn.com; www.imaps.org.

21–26 44th SVC Conf., *Philadelphia, PA.* Society of Vacuum Coaters, 71 Pinon Hill Place, N.E., Albuquerque, NM 87122-1914; 505-856-7188; 505-856-6716; e-mail svcinfo@svc.org.

22–25 ACerS 103rd Annual Meeting, *Indianapolis, IN.* American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-794-5890; fax 614-899-6109; e-mail customersrvc@acers.org; www.ceramics.org.

22–25 Conf. on Materials and Science in Sports, *Coronado, CA.* F.H. Froes, Univ. of Idaho, Inst. of Materials and Advanced Proc., Mines Bldg., Rm. 321, Moscow, ID 83844-3026; 208-885-7989; fax 208-885-4009; e-mail imap@uidaho.edu.

22–26 6th Intl. Workshop on Fabrication, Characterization, and Modeling of Ultra-Shallow Doping Profiles in Semiconductors, *Napa Valley, CA.* D. Miller, AVS West, 1265 El Camino Real, Ste. 109, Santa Clara, CA 95050; 408-246-3600; fax 408-246-7700; e-mail della@vacuum.org; www.vacuum.org.

22–26 AIChE Spring National Meeting, *Houston, TX.* Meetings Dept., American Inst. of Chemical Engineers, 3 Park Ave., New York, NY 10016-5991; 212-591-7338; fax 212-591-8894; e-mail meetmail@aiche.org; www.aiche.org/conferences/.

23–24 12th IEEE/SEMI Advanced Semiconductor Manufacturing Conf., *Munich, Germany.* M. Kindling,, Semiconductor Equipment and Materials Intl., 805 15th St. N.W., Ste. 810, Washington, DC 20005; 202-289-0440; fax 202-289-0441; e-mail mkindling@semi.org; www.semi.org.

23–27 13th Intl. Conf. on Wear of Materials, *Vancouver, Canada.* A. Hill, Conf. Secretariat; Elsevier Science, the Boulevard, Langford Lane, Kidlington, Oxford, Oxon OX5 1GB, UK; 44-1865-843-643; fax 44-1865-843-958; e-mail a.richardson@elsevier.co.uk; www.elsevier.com/locate/wom.

23–27 APS April Meeting, *Washington, DC.* American Physical Society, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3200; fax 301-209-0865; www.aps.org.

24–29 27th Annual Meeting of the Society For Biomaterials, *St. Paul, MN.* Society For Biomaterials, 13355 10th Ave. North, Ste. 108, Minneapolis, MN 55441-5510; 763-543-0908; fax 763-545-0335; www.biomaterials.org.

28–1 APS April Meeting, *Washington, DC.* American Physical Society, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3200; fax 301-209-0865; e-mail meetings@aps.org; www.aps.org.

30–4 ▼ Intl. Conf. on Metallurgical Coatings and Thin Films, *San Diego, CA.* M.S. Gray, ICMCTF, Ste. 136, 14001-C Saint Germain Dr., Centreville, VA 20120; 703-266-3287; fax 703-968-8877; e-mail icmctf@mindspring.com; www.vacuum.org/icmctf/icmctf.html.

MAY 2001

5–7 ▼ 13th Annual Intl. Scientific Meeting on Scanning Microscopies, *New York, NY.* FAMS, P.O. Box 832, Mahwah, NJ 07430-0832; 201-818-1010; fax 201-818-0086; e-mail scanning@fams.org; www.scanning.org.

6–10 SAMPE 2001 Symposium, *Long Beach, CA.* Society for the Advancement of Material and Process Engineering, P.O. Box 2459, Covina, CA 91722-8459; 626-331-0616; fax 626-332-8929; e-mail sampereg@aol.com; www.sampe.org.

6–11 Conf. on Lasers and Electro-Optics, and Quantum Electronics and Laser Science Conf., *Baltimore, MD.* Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., N.W., Washington, DC 20036-1023; 202-416-1980; fax 202-416-6100; e-mail confserv@osa.org; www.osa.org/mtg_conf.

8 IMAPS New England 28th Annual Symposium, *Boxborough, MA.* D. D'Ambra, Technical Program Chair, 26 Winterberry Dr., Franklin, MA 02038; e-mail David.M.DAmbra@usa.dupont.com; http://imapsne.org.

9–11 14th Radio Frequency Topical Conf., *Oxnard, CA.* T.K. Mau, Univ. of California at San Diego, Fusion Energy Research Program, Rm. 460, EBU-II, 9500 Gilman Dr., La Jolla, CA 92093-0417; 858-534-2880; fax 858-534-7716; e-mail mau@aries.ucsd.edu; www-ferp.ucsd.edu/–mau/RF2001.

12–17 16th Intl. Conf. on Cyclotrons and Their Applications, *East Lansing, MI.* F. Marti, Natl. Superconducting Cyclotron Lab., Michigan State Univ., East Lansing, MI 48824-1321; fax 517-353-5967; e-mail marti@ncsl.msu.edu.

13–16 ▼ 14th Intl. Symposium on Preparative/Process Chromatography, *Washington, DC.* J. Cunningham, Barr Enterprises, P.O. Box 279, Walkersville, MD 21793; 301-898-3772; fax 301-898-5596; e-mail janetbarr@aol.com; www.prepsymposium.org.

13–17 ▼ Intl. Conf. on Powder Metallurgy and Particulate Materials, *New Orleans, LA.* Metal Power Industries Federation, APMI Intl., 105 College Rd. East, Princeton, NJ 08540-6692; 609-452-7700; fax 609-987-8523; www.mpif.org.

13–18 ▼ 1st Intl. Conf. and School on Spintronic and Quantum Information Technology, *Maui, HI.* www.sainc.com/spintech1.

14–15 Conf. on Materials Science and Engineering: Its Nucleation and Growth, *London, UK.* M. McLean, Dept. of Materials, Imperial College of Science, Technology, and Medicine, Prince Consort Rd., London SW7 2BP, UK, fax 44-20-7594-6736; e-mail m.mclean@ic.ac.uk.

16–25 Sikkim Intl. Nanotribology Symposium, *Sikkim, India.* S.K. Biswas, Dept. Mechanical Engineering, Indian Institute of Science, Bangalore 560012, India; 91-80-3600586/3092963; fax 91-80-3600648; nanosikkim@mecheng.iisc.ernet.in; www.mecheng.iisc.ernet.in/nanosikkim.html.

20–22 ▼ ACerS Structural Clay Products Div. Meeting, *Canton, OH.* The American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-794-5890; fax 614-899-6109; e-mail customersrvc@acers.org; www.ceramics.org.

21–23 3rd Intl. Symposium on Polymer Surface Modification, *Newark, NJ.* R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 845-226-1393; fax 212-656-1016; e-mail rhl@mstconf.com; http://mstconf.com/surfmod3.htm.

21–25 ▼ 9th Intl. Symposium on Gaseous Dielectrics, *Elliott City, MD.* T. Vicente, NIST, 100 Bureau Dr., Stop 3461, Gaithersburg, MD 20899-3461; 301-975-3882; fax 301-948-2067; e-mail loucas.christophorou@nist.gov; www.eeel.nist.gov/dielectrics_ix/.

23–25 4th Intl. Conf. on Marine Technology, *Szczecin, Poland.* K. Savage, Wessex Inst. of Technology, WIT Marketing Coordinator, Ashurst Lodge, Ashurst, Southampton SO40 7AA, UK; 44-238-029-3223; fax 44-238-029-2853; e-mail ksavage@wessex.ac.uk.

24 MBC Science Symposium, *Boston, MA.* Massachusetts Biotechnology Council, 1 Cambridge Ctr., 4th Floor, Cambridge, MA 02142; 617-577-8198; fax 617-577-7860; www.massbio.org.

24–25 Intl. Symposium on Surface Contamination and Cleaning, *Newark, NJ.* R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 845-226-1393; fax 212-656-1016; e-mail rhl@mstconf.com; http://mstconf.com/surfclean.htm.

26–30 ▼ 84th Canadian Society for Chemistry Conf., *Montreal, Quebec, Canada.* Y.S. Tsantrizos, Dept. of Chemistry, Boehringer Ingelheim (Canada), 2100 Cunard St., Laval, PQ H7S 2G5, Canada; 613-232-6252; fax 613-232-5862; e-mail ytsantrizos@lav.boehringer-ingelheim.com; www.csc2001.chemistry.ca.

27–31 ▼ 49th ASMS Conf. on Mass Spectrometry, *Chicago, IL.* American Society for Mass Spectrometry, 1201 Don Diego Ave., Santa Fe, NM 87505; 505-989-4517; fax 505-989-1073; e-mail asms@asms.org; www.asms.org.

28–1 15th Intl. PLANSEE Seminar: Powder Metallurgical High Performance Materials, *Reutte, Austria.* P. Rodhammer, Conf. Secretary, PLANSEE Holding AG, A-6600 Reutte, Austria; 43-5672-600-2800; fax 43-5672-600-62800; e-mail plansee.seminar@plansee.at; www.plansee.com.

30–1 13th European Microelectronics and Packaging Conf., *Strasbourg, France.* Intl. Microelectronics and Packaging Society, 1850 Centennial Park Dr., Ste. 105, Reston, VA 20191-1517; 888-464-6277; fax 703-758-1066; www.imaps.org.

30–1 Intl. Symposium on Microelectronic and MEMS Technology, *Edinburgh, Scotland.* SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

JUNE 2001

3–6 ▼ Symposium on New Technology in Computer Applications for the Steel Industry, *Myrtle Beach, SC.* Iron & Steel Society, 186 Thorn Hill Rd., Warrendale, PA 15086-7528; 724-776-1535; fax 724-776-0430; e-mail custserv@iss.org; www.iss.org.

3–8 Conf. on Structure and Mechanical Properties of Nanostructured Materials, *Barga, Italy.* The United Engineering Foundation, 3 Park Ave., 27th Floor, New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.engfnd.org.

4–7 ▼ 10th Intl. Workshop on Critical Currents, *Göttingen, Germany.* H.C. Freyhardt, Inst. für Materialphysik Windausweg 2, 37073 Göttingen, Germany; 49-551-50717-0; fax 49-551-50717-50; e-mail hfreyha@gwdg.de; www.iwcc2001.uni-goettingen.de.

5–7 PLASTEC™ East Plastics Conf., co-located with Medical Design & Manufacturing East and Atlantic Design & Manufacturing Conf., *New York, NY.* Canon Communications, 11444 W. Olympic Blvd., Ste. 900, Los Angeles, CA 90064; 310-996-9447; 310-996-9499; www.canontradeshows.com.

5–8 **E-MRS Spring Meeting,** *Strasbourg, France.* E-MRS, B.P. 20, 67037 Strasbourg Cedex 2, France; 33-3-8810-6372; fax 33-3-8810-6343; e-mail emrs@phase.c-strasbourg.fr; www-emrs.c-strasbourg.fr. **E-MRS**.

6–8 Conf. on Optical Engineering for Sensing and Nanotechnology, *Yokohama, Japan.* SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

10–13 75th Colloid and Surface Science Symposium, *Pittsburgh, PA.* S. Garoff, 412-268-6877; fax 412-681-0648; e-mail sg2e@andrew.cmu.edu; http://colloids2001.cheme.cmu.edu.

10–14 EUROMAT 2001 Conf., *Rome, Italy.* AIM, Piazzale Rodolfo Morandi 2-1-20121 Milano, Italy; 39-2-7639-7770; fax 39-2-7602-0551; e-mail aim@fast.mi.it; www.fast.mi.it/aim/euromat.htm.

11–15 Natl. Space and Missile Materials Symposium, *Monterey, CA.* Space and Missile Materials Symposium, c/o Anteon Corp., 5100 Springfield St., Ste. 509, Dayton, OH 45431; 937-254-7950; fax 937-253-2296; e-mail diana.carlin@kirtland.af.mil; www.usasymposium.com/space2/index.htm.

13–15 3rd Intl. Symposium on Acid-Base Interactions, *Newark, NJ.* R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 845-226-1393; fax 212-656-1016; e-mail rhl@mstconf.com; http://mstconf.com/acidbase3.htm.

13–15 ▼ 6th Intl. Symposium on Sputtering and Plasma Processes, *Kanazawa, Japan.* E. Kusano, ISSP 2001 Committee, Advanced Materials Science Ctr., Kanazawa Inst. of Technology, 3-1 Yatsukaho Matto, Ishikawa 924-0838, Japan; 81-76-274-9250; fax 81-76-274-9251; e-mail issp@wwwr.kanazawa-it.ac.jp; wwwr.kanazawa-it.ac.jp/issp/.

17–20 5th Intl. Special Emphasis Symposium on Superalloys 718, 625, 706, and Derivatives, *Pittsburgh, PA.* TMS, 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail tmsgeneral@tms.org; www.tms.org/cms.

18–20 ▼ 2nd Intl. Conf. on Cellular Metals and Metal Foaming Technology, *Bremen, Germany.* Fraunhofer-Inst. IFAM, MetFoam 2001 Conf. Secretariat, Wiener Str. 12, D-28359 Bremen, Germany; 49-421-2246-0; fax 49-421-2246-300; e-mail metfoam@ifam.fhg.de; www.ifam.fhg.de.

18–20 3rd Intl. Symposium on Silanes and Other Coupling Agents, *Newark, NJ.* R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 845-226-1393; fax 212-656-1016; e-mail rhl@mstconf.com; http://mstconf.com/silane3.htm.

18–21 ▼ 7th Intl. Conf. on Architectural and Automotive Glass, *Tampere, Finland.* J. Vitkala, Conf. Chairman, Tamglass Ltd. Oy, Vehmaistenkatu 5, 33730 Tampere, Finland; 358-3-372-3111; fax 358-3-372-3180; e-mail jorma.vitkala@tamglass.com; www.glassprocessingdays.com.

19–21 6th Intl. Workshop on Plasma-Based Ion Implantation, *Grenoble, France.* Y. Pauleau, CNRS-LEMD, B.P. 166, 25 Rue des Martyrs, 38042 Grenoble Cedex 9, France; 33-4-7688-1071; fax 33-4-7688-7945; e-mail pauleau@polycnrs-gre.fr; www.polycnrs-gre.fr.

20–22 Conf. on Laser and Laser Information Technology, *Vladimir, Russia.* SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

23–30 12th APS Topical Conf. on Shock Compression of Condensed Matter, *Atlanta, GA.* A. Roach, Los Alamos Natl. Lab.; 505-665-6277; e-mail alita@lanl.gov.

24–27 **2001 International Workshop on Superconductivity (ISTEC)**, *Honolulu, Hawaii.* Workshop Coordinators: Tetsuji Kobayashi, ISTEC and Elton N. Kaufmann, Argonne National Laboratory; fax 81-3-3431-4044; e-mail t-kobayashi@istec.or.jp; www.istec.or.jp/ISTEC_homepage/WORK/e-workshop.html. **MRS**.

24–30 Intl. Workshop on High-Temperature Superconductors and Novel Inorganic Materials Engineering, *Moscow-St. Petersburg, Russia.* R.V. Shpanchenko, MSU-HTSC VI Secretariat, Dept. of Chemistry, Moscow State Univ., 119899 Moscow, Russia; 7-095-939-3490; fax 7-095-939-4788; e-mail roms@icr.chem.msu.ru; http://icr.chem.msu.ru/htsc6.htm.

25–27 ▼ 59th Annual Device Research Conf., *Notre Dame, IN.* A. Seabaugh, Univ. of Notre Dame, Dept. of Electrical Engineering, 266 Fitzpatrick Hall, Notre Dame, IN 46556; 219-631-4473; fax 219-631-4393; e-mail seabaugh.1@nd.edu; www.tms.org/Meetings/Specialty/DRC/2001/DRC-2001-Home.html.

25–27 ▼ Intl. Workshop on Nanocapillarity: Wetting of Heterogeneous Surfaces and Porous Solids, *Princeton, NJ.* e-mail info@triprinceton.org; www.triprinceton.org/workshop2001.

25–28 2nd European Cells and Materials Meeting, *Davos, Switzerland.* Conf. Secretary, AO ASIF Research Inst., Clavadelerstrasse, CH7270, Davos Platz, Switzerland; www.aoasif.ch/events/other/ecm/index.shtml.

25–28 Natl. Space and Missile Materials Symposium, *Monterey, CA.* Space and Missile Symposium, c/o Anteon Corp., 5100 Springfield St., Ste. 509, Dayton, OH 45431; 937-254-7950; fax 937-253-2296; www.usasymposium.com.

26–1 17th Intl. Conf. on Coherent and Nonlinear Optics, *Minsk, Belarus.* SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

27–29 ▼ Conf. on Mechanics and Materials, *San Diego, CA.* L. Jacobs-Cohants, Univ. of California at San Diego, Ctr. of Excellence for Advanced Materials, 9500 Gilman Dr., La Jolla, CA 92093-0416; 858-534-4772; fax 858-534-2727; e-mail ljacobs@halebopp.ucsd.edu; www-ceam.ucsd.edu/mmc2001.

27–29 Electronic Materials Conf., *Notre Dame, IN.* TMS, 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail tmsgeneral@tms.org; www.tms.org/cms.

JULY 2001

1–6 **Conf. on Advances in Environmental Materials, and Intl. Conf. on Materials for Advanced Technologies**, *Singapore.* E-mail tjwhite@eti.org.sg; www.mrs.org.sg/icmat2001. **MRS-S**.

1–6 Gordon Research Conf. on Materials Processes Far from Equilibrium, *Andover, NH.* Gordon Research Conferences, Univ. of Rhode Island, P.O. Box 984, West Kingston, RI 02892-0984; e-mail app@grcmail.grc.uri.edu; www.grc.uri.edu/regpay/reg.htm.

2–6 ▼ Conf. on Coatings Science and Technology, *Athens, Greece.* Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 845-255-0757; fax 845-255-0978; e-mail info@ims-np.org; http://ims-np.org/.

2–6 Conf. on Electric Charges in Nonconductive Materials, *Tours, France.* SFV Div. Dielectriques, 19 Rue du Renard, 75004 Paris, France; 33-153-019-030; fax 33-142-786-320; e-mail sfv@vide.org. www.vide.org/CSC4.html.

2–6 ▼ Intl. Conf. on Fuel Cells, *Lucerne, Switzerland.* European Fuel Cell Forum, P.O. Box 99, CH-5452 Oberrohrdorf, Switzerland; 41-56-496-7292; fax 41-56-496-4412; e-mail info@efcf.com; www.efcf.com.

15–21 21st IUPAP Intl. Conf. on Statistical Physics, *Cancun, Mexico.* A. Robledo, IFUNAM, Apartado Postal 20-364, Mexico 01000, D.F., Mexico; 525-622-5095; fax 525-622-5008; e-mail statphys@varea.ifisicacu.unam.mx; http://varea.ifisicacu.unam.mx/statphys21.htm.

16–20 **4th Intl. Conf. on Nitride Semiconductors** (ICNS-4), *Denver, CO.* Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086; 724-779-3003; fax 724-779-8313; e-mail info@mrs.org.; www.mrs.org. **MRS**.

16–20 21st Int. Conf. on Defects in Semiconductors, *Giessen, Germany.* ICDS 21, D. Musaeus, I. Physikalisches Inst., Heinrich-Buff-Ring 16, D-35392 Giessen, Germany; e-mail ICDS21@physik.uni-giessen.de; www.uni-giessen.de/icds21.

16–20 Cryogenic Engineering Conference & International Cryogenic Materials Conference (CEC-ICMC), *Madison, WI.* Centennial Conferences, 4800 Baseline Road, A-112, Boulder, CO 80303 USA; 303-499-2299; fax 303-499-2599; e-mail cec-icmc@centennialconferences.com; www.cec-icmc.org

18–24 22nd Intl. Conf. on Photonic, Electronic, and Atomic Collisions, *Santa Fe, NM.* S. Datz, Oak Ridge Natl. Lab., P.O. Box 2008, Oak Ridge, TN; 865-574-4984; fax 865-574-1118; e-mail icpeac@phy.ornl.gov; http://icpeac2001.phy.ornl.gov.html.

21–26 Natl. Meeting of the American Crystallographic Association, *Los Angeles, CA.* D. McRee, Dept. of Molecular Biology, Scripps Research Inst., La Jolla, CA 92037; 619-784-9235; fax 619-784-2857; e-mail dem@scripps.edu; www.hwi.buffalo.edu/ACA/ACA-Annual/LosAngeles/LosAngeles.html.

22–26 10th Intl. Conf. on Intergranular and Interphase Boundaries, *Haifa, Israel.* W. Kaplan, Dept. of Materials Engineering, Technion, Israel Inst. of Technology, Haifa 32000, Israel; 972-4-829-4580; fax 972-4-832-1978; e-mail kaplan@tx.technion.ac.il; http://iib2001.technion.ac.il.

23–27 13th Intl. Conf. on Vacuum UV Radiation Physics, *Trieste, Italy.* e-mail renato.gioppo@elettra.trieste.it; vuv13.elettra.trieste.it/vuv13/.

25–27 ▼ 6th Intl. Workshop on Stress-Related Effects in Metallizations, *Ithaca, NY.* Stress Workshop, Bard Hall, Cornell Univ., Ithaca, NY 14853; 607-255-4135; fax 607-255-2365; e-mail stressworkshop@cornell.edu; http://stressworkshop.cornell.edu.

29–3 19th Intl. Conf. on Atomic Collisions in Solids, *Paris, France.* V.A. Esaulov, Lab. des Collisions Atomiques et Moleculaires, Bat. 351, Univ. de Paris Sud, 91405 Orsay Cedex, France; 33-69-15-76-80; fax 33-69-15-76-71; e-mail icacs19@veof1.lcam.u-psud.fr; http://veof1.lcam.u-psud.fr/idc/icacs19.html.

29–3 Intl. Conf. on High-Performance Materials in Bridges and Buildings, *Kona, HI.* United Engineering Foundation, 3 Park Ave., 27th Floor, New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.engfnd.org.

29–3 SPIE Annual Meeting and Intl. Symposium on Optical Science and Technology, *San Diego, CA.* SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

30–3 4th Intl Conf. on Biological Physics, *Kyoto, Japan.* M. Go, Div. of Biological Science, Graduate School of Science, Nagoya Univ., Furo-cho, Chikusa-ku, Nagoya 464-8602, Japan; e-mail icbp2001@kokusai.phys.nagoya-u.ac.jp; kokusai.phys.nagoya-u.ac.jp/.

30–3 Nonneutral Plasma Physics Workshop, *La Jolla, CA.* C.F. Driscoll, Organizing Committee Chair, Univ. of California at San Diego, Physics Dept., 0319, 9500 Gilman Dr., La Jolla, CA 92093-0319; 858-534-2489; fax 858-534-0173; e-mail fdriscol@ucsd.edu; http://sdphCA.ucsd.edu/NNP/.

AUGUST 2001

5–9 10th Intl. Conf. on Environmental Degradation of Materials in Nuclear Power Systems-Water Reactors, *South Lake Tahoe, NV.* NACE Intl., P.O. Box 218340, Houston, TX 77218-8340; 281-228-6223; e-mail msd@mail.nace.org; www.nace.org.

5–9 ▼ Conf. on Microscopy and Microanalysis, *Long Beach, CA.* MSA Meeting Managers, 7000 W. Southwest Hwy., Chicago Ridge, IL 60415; 708-361-6045; fax 708-361-6166; e-mail msa@tradeshownet.com; www.mmconference.org/2001.

6–8 ▼ 26th Intl. Thermal Conductivity Conf. and 14th Intl. Thermal Expansion Symposium, *Cambridge, MA.* Conf. Chair, ITCC 26/ITES 14, c/o Holometrix Micromet, 25 Wiggins Ave., Bedford, MA 01730; itcc@holometrix.com; www.thermalconductivity.com.

12–17 10th Intl. Conf. on Phonon Scattering in Condensed Matter, *Hanover, NH.* Phonons 2001, Dept. of Physics and Astronomy, Dartmouth College, HB 6127, Hanover, NH 03755; e-mail phonons@mac.dartmouth.edu; www.dartmouth.edu/–phonon.

13–17 10th Canadian Semiconductor Technology Conf., *Ottawa, Ontario,* Canada. M. Lanouette, Conf. Mgr., Conf. Services Office, Natl. Research Council Canada, Bldg. M-19, Ottawa, Ontario, Canada K1A 0R6; 613-993-0414; fax 613-993-7250; e-mail marie.lanouette@nrc.ca.

26–30 ▼ **7th Intl. Conf. on Advanced Materials**, *Cancun, Mexico.* M.L. Marquina, Dept. de Física, Facultad de Ciencias, Univ. Nacional Autónoma de México, 04510 México, D.F.; e-mail committee@icam2001.unam.mx; www.icam2001.unam.mx. **IUMRS.**

26–30 ▼ 222nd American Chemical Society Natl. Meeting, *Chicago, IL.* Dept. of Meetings, American Chemical Society, 1155-16th St., NW, Washington, DC 20036; 202-872-4396; fax 202-872-6128; e-mail natlmtgs@acs.org.

26–31 13th European Conference on Chemical Vapor Deposition (EUROCVD13), *Athens, Greece.* www.imel.demokritos.gr/EUROCVD/Eurocvd13.html.

27–31 Conf. on Recrystallization and Grain Growth, *Aachen, Germany.* D.A. Molodov, Inst. für Metallkunde und Metallphysik, RWTH Aachen, D-52056 Aachen, Germany; fax 49-241-888-8608; e-mail ReX&GG@imm.rth-aachen.de.

SEPTEMBER 2001

2–7 200th Meeting of the Electrochemical Society and 52nd Meeting of the Intl. Society of Electrochemistry, *San Francisco, CA.* The Electrochemical Society, 65 S. Main St., Pennington, NJ 08534-2839; 609-737-1902; fax 609-737-2743; e-mail ecs@electrochem.org; www.electrochem.org.

3–7 ▼ 11th Intl. Conf. on Radiation Effects in Insulators, *Lisbon, Portugal.* Conf. Secretariat REI-11, Inst. Tecnológico e Nuclear, Estrada Nacional No. 10, 2686-953, Sacavém, Portugal; 351-21-994-6000; fax 351-21-994-1525; e-mail REI-11@itn.pt; www.itn.pt/REI11/.

3–14 ▼ Conf. on Chemical Physics of Thin Film Deposition Processes for Micro- and Nano-Technologies, *Kaunas, Lithuania.* Y. Pauleau, CNRS-LEMD, B.P. 166, 25 Rue des Martyrs, 38042 Grenoble Cedex 9, France; 33-4-7688-1071; fax 33-4-7688-7945; e-mail pauleau@polycnrs-gre.fr. www.polycnrs-gre.fr.

9-13 Power Quality Conf., *Rosemont (Chicago), IL.* Power Quality 2001, 2472 Eastman Ave. #33, Ventura, CA 93003-5792; fax 805-650-7054; e-mail linda@powersystems.com; www.powersystems.com/cfp/2001/pq.html.

9–14 ▼ 10th Intl. Conf. on II-VI Compounds, *Bremen, Germany.* H. Heinke, Secretary II-VI 2001, Inst. for Solid State Physics, Univ. of Bremen, FB1, P.O. Box 330 440, D-28334 Bremen, Germany; 49-421-218-7453; fax 49-421-218-4581; e-mail II-VI2001@physik.uni-bremen.de; www.II-VI2001.uni-bremen.de.

9–14 Conf. on Surface Modification of Materials by Ion Beams, *Marburg, Germany.* D. Rueck, Gesellschaft für Schwerionenforschung mbH, Planckstrasse 1, D-64291 Darmstadt, Germany; 49-6159-71-2603; fax 49-6159-71-2505; e-mail D. Rueck@gsf.de; www.gsi.de.

11–14 ▼ Intl. Symposium on High-Performance Liquid Phase Separation, *Kyoto, Japan.* N. Tanaka, Kyoto Inst. of Technology, Kyoto, Japan; e-mail hplckit@ipc.kit.ac.jp.

12–14 ▼ 2nd Intl. Conf. on High-Resolution and Magnetic Sector Field ICP-MS, *Vienna, Austria.* T. Prohaska, Inst. für Chemie, Univ. für Bodenkultur, BOKU-Wien, Muthgasse 18, A-1190 Vienna, Austria; 43-1-36006-6092; fax 43-1-36006-6059-092; e-mail prohaska@mail.boku.ac.at; www.boku.ac.at/chemie/conferences/conferences.htm.

12–14 ▼ **Jornadas SAM-CONAMET 2001**, *Posadas, Argentina.* Jornadas SAM-CONAMET 2001, Facultad de Ciencias Exáctas, Químicas y Naturales, Azara 1552, 3300 Posadas, Misiones, Argentina. **MRS-A.**

14–16 4th Intl. Conf. on Peer Review in Biomedical Publication, *Barcelona, Spain.* A. Flanagin, JAMA, 515 N. State St., Chicago, IL 60610; 312-464-2432; fax 312-464-5824; e-mail jama-peer@ama-assn.org.

16–21 **Intl. Conf. on Hydrogen Effects on Material Behavior and Corrosion Deformation Interactions**, *Moran, WY.* N.R. Moody, SNL, P.O. Box 969, MS-9404, Livermore, CA 94551; 925-294-2622; fax 925-294-3410. **Endorsed.**

17–20 ▼ 5th Intl. Airborne Remote Sensing Conf., *San Francisco, CA.* Veridian Systems Intl. Conferences, P.O. Box 134008, Ann Arbor, MI 48113-4008; 734-994-1200; fax 734-994-5123; www.erim-int.com/CONF/IARSC.html.

17–21 Conf. on X-Ray and Neutron Capillary Optics, *Zvenigorod, Russia.* SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

17–21 Intl. Symposium on Advanced Materials, *Islamabad, Pakistan.* A.A. Mazhar, Secretary Symposium, A.Q. Khan Res. Lab., Kahuta, P.O. Box 905, Rawalpindi, Pakistan, 92-51-928-0541; fax 92-51-928-0542; e-mail compudiv@asb.paknet.com.pk.

18–21 Intl. Conf. on Advances in Materials and Processing Technologies, *Madrid, Spain.* AMPT'01 Congress Secretariat, Fundación Univ. Carlos III, CON-GREGA, Avda. de la Universidad 30, 28911 Leganés, Spain; 34-91-624-9142; fax 34-91-624-9147; e-mail congrega@fund.uc3m.es; e-mail ampt01@ing.uc3m.es.

23–26 TMS Fall Extraction and Process Metallurgy Meeting, *San Diego, CA.* M. Cross, School of Computing and Mathematical Science, Univ. of Greenwich, Woolwich Campus, Wellington St., Woolwich, London SE18 6PF, UK; 44-208-331-8702; fax 44-208-331-8695.

23–27 3rd Intl. Symposium on Structural Intermetallics, *Jackson Hole, WY.* TMS, 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail tmsgeneral@tms.org; www.tms.org/meetings/.

23–27 6th World Congress of Chemical Engineering, *Melbourne, Australia.* Meetings Dept., American Inst. of Chemical Engineers, 3 Park Ave., New York, NY 10016-5991; 212-591-7338; fax 212-591-8894; e-mail meetmail@aiche.org; www.aiche.org/conferences/.

23–27 ACS Southeast Regional Meeting, *Savannah, GA.* American Chemical Society, 1115 16th St., NW, Washington, DC 20036; 202-872-4600; fax 202-872-4615; e-mail help@acs.org; www.acs.org.

OCTOBER 2001

1–3 ▼ Conf. on Fine Powder Processing, *State College, PA.* C. Knobloch, Particle Materials Ctr., The Pennsylvania State Univ., 225 Materials Research Lab., University Park, PA 16802-4801; 814-863-6156; fax 814-863-9704; e-mail clk18@psu.edu; conferenceinfo@cde.psu.edu.

3–5 Conf. on Photomask Technology and Management, *Monterey, CA.* SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

5–12 ▼ 28th Annual Conf. on Federation of Analytical Chemistry and Spectroscopy Societies, *Detroit, MI.* C. Lilly, FACSS Natl. Office, 1201 Don Diego Ave., Santa Fe, NM 87505; 508-820-1648; fax 505-989-1073; e-mail jsjoberg@trail.com; http://facss.org/info.html.

7–12 ▼ Conf. on Structural Ceramics and Ceramic Composites for High-Temperature Applications, *Seville, Spain.* United Engineering Foundation, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.engfnd.org.

10–13 ACS Midwest Regional Meeting, *Lincoln, NE.* American Chemical Society, 1115 16th St., NW, Washington, DC 20036; 202-872-4600; fax 202-872-4615; e-mail help@acs.org; www.acs.org.

14–18 6th Intl. Symposium on Self-Propagating High-Temperature Synthesis, *Haifa, Israel.* Dept. of Materials Engineering, TECHNION–Israel Inst. of Technology, Technion City, Haifa 32000, Israel; 972-4-829-2112; fax 972-4-832-1978; e-mail gutmanas@tx.technion.ac.il; www.technion.ac.il/technion/materials.

15–18 ▼ 20th Intl. Congress on Applications of Lasers and Electro-Optics, *Jacksonville, FL.* B. Cohen, Laser Inst. of America, 13501 Ingenuity Dr., Ste. 128, Orlando, FL 32826; 407-380-1553; fax 407-380-5588; e-mail lia@laserinstitute.org; www.icaleo.org.

17–20 ACS Southwest Regional Meeting, *San Antonio, TX.* American Chemical Society, 1115 16th St., NW, Washington, DC 20036; 202-872-4600; fax 202-872-4615; e-mail help@acs.org; www.acs.org.

17–20 Fall Meeting of the APS Division of Nuclear Physics, *Maui, HI.* American Physical Society, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3200; fax 301-209-0865; www.aps.org.

21–25 ▼ Intl. Workshop on Flow and Fracture of Advanced Glasses, *Rennes, France.* V. Keryvin, Univ. Rennes1, Larmaur, 35042 Rennes, France; 33-2-9928-2685; fax 33-2-9928-1600; e-mail vincent.keryvin@univ-rennes1.fr; www.larmaur.univ-rennes1.fr/ffag.

22–23 ▼ North American Orbital Welding Symposium, *Rosemont, IL.* Astro Arc Polysoude, W133 N5138 Campbell Dr., Menomonee Falls, WI 53051; 414-783-2720; fax 414-783-2730; e-mail mbaer@polysoude.com; www.polysoude.com.

22–24 ▼ Powder Metallurgy Congress, *Nice, France.* European Powder Metallurgy Assoc., Old Bank Bldgs., Bellstone, Shrewsbury SY1 1HU, UK; 44-1743-248-899; fax 44-1743-362-968; e-mail info@epma.com; www.epma.com.

22–26 ▼ OSA Annual Meeting and 16th Interdisciplinary Laser Science Conf., *Providence, RI.* Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., NW, Washington, DC 20036-1023; 202-223-8130; fax 202-223-1096; e-mail confserv@osa.org; www.osa.org/mtg_conf/annual.

28–31 ▼ 43rd Mechanical Working and Steel Processing Conf., *Charlotte, NC.* Iron & Steel Society, 186 Thorn Hill Rd., Warrendale, PA 15086-7528; 724-776-1535; fax 724-776-0430; e-mail custserv@iss.org; www.iss.org.

28–31 ACS Western Regional Meeting, *Santa Barbara, CA.* American Chemical Society, 1115 16th St., NW, Washington, DC 20036; 202-872-4600; fax 202-872-4615; e-mail help@acs.org; www.acs.org.

28–2 ▼ Intl. Conf. on Silicon Carbide and Related Materials, *Tsukuba, Japan.* H. Okumura, Electrotechnical Lab., 1-1-4 Umezono, Tsukuba, Ibaraki 305-8565, Japan; www.icscrm2001.gr.jp/.

29–2 ▼ 48th Natl. American Vacuum Society Symposium, *San Francisco, CA.* American Vacuum Society Natl. Office, 120 Walls St., 32nd Fl., New York, NY 10005; 212-248-0200; fax 212-248-0245; e-mail avsnyc@vacuum.org; www.vacuum.org.

29–2 Meeting of the APS Div. of Plasma Physics, *Long Beach, CA.* APS Headquarters, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3200; fax 301-209-0865; e-mail meetings@aps.org; www.aps.org.

NOVEMBER 2001

4–8 33rd Intl. SAMPE Technical Conf., *Seattle, WA.* Society for the Advancement of Material and Process Engineering, P.O. Box 2459, Covina, CA 91722-8459; 626-331-0616; fax 626-332-8929; e-mail sampereg@aol.com; www.sampe.org.

4–8 Intl. Conf. on Advanced Ceramics and Glasses, *Maui, HI.* American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-890-4700; fax 614-899-6109; e-mail info@acers.org; www.acers.org/meetings/.

4–8 TMS Fall Meeting, *Indianapolis, IN.* TMS, 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail weissp@tms.org; www.tms.org.

4–9 AIChE Annual Meeting, *Reno, NV.* Meetings Dept., American Inst. of Chemical Engineers, 3 Park Ave., New York, NY 10016-5991; 212-591-7338; fax 212-591-8894; e-mail meetmail@aiche.org; www.aiche.org/conferences/.

5–7 2nd Intl. Symposium on Adhesion Aspects of Thin Films, *Newark, NJ.* R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 845-226-1393; fax 212-656-1016; e-mail rhl@mstconf.com; http://mstconf.com/adhtf2.htm.

7–9 3rd Intl. Symposium on Adhesion Measurement of Thin Films and Coatings, *Newark, NJ.* R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 845-226-1393; fax 212-656-1016; e-mail rhl@mstconf.com; http://mstconf.com/adhmeas3.htm.

11–14 ▼ 59th Electric Furnace Conf., *Phoenix, AZ.* The American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-794-5890; fax 614-899-6109; e-mail customersrvc@acers.org; www.ceramics.org.

26–30 **MRS Fall Meeting**, *Boston, MA.* Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail info@mrs.org; www.mrs.org. **MRS**.

DECEMBER 2001

3–5 2nd Intl. Symposium on Polyimides and Other High Temperature Polymers, *Newark, NJ.* R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 845-226-1393; fax 212-656-1016; e-mail rhl@mstconf.com; http://mstconf.com/polyimd2.htm.

3–7 10th Intl. Congress of Fracture, *Honolulu, HI.* A. Hill, ICF10 Congress Secretariat, Elsevier Science, The Boulevard, Langford Lane, Kidlington, Oxford OX5 1GB, UK; 44-1865-843-643; fax 44-1865-843-958; e-mail a.richardson@elsevier.co.uk; www.elsevier.com.

5–8 3rd Intl. Symposium on Environmental Hydraulics, *Tempe, AZ.* R. Rankin, ISEH 2001 Secretary, Arizona State Univ., Dept. of Mechanical and Aerospace Engineering, P.O. Box 876106, Tempe, AZ 85287-6106; 480-965-3207; fax 480-965-1384; e-mail iseh@enpop2.eas.asu.edu; www1.eas.asu.edu/~iseh2001/.

6–7 8th Intl. Symposium on Metallized Plastics, *Newark, NJ.* R.H. Lacombe, Conf. Chairman, 3 Hammer Dr., Hopewell Junction, NY 12533; 845-226-1393; fax 212-656-1016; e-mail rhl@mstconf.com; http://mstconf.com/metalplas8.htm.

11–15 4th Pacific Rim Intl. Conf. on Advanced Materials and Processing, *Honolulu, HI.* S. Hanada, Tohoku Univ., Inst. for Materials Research, Katahira 2-1-1, Aoba-ku, Sendai 980-8577, Japan; 81-22-215-2115; fax 81-22-215-2116; e-mail ccpricm4@imr.tohoku.ac.jp.

JANUARY 2002

6–11 13th Intl. Conf. on Ternary and Multinary Compounds, *Dead Sea, Israel.* D. Cahen, Dept. of Materials and Interfaces, Weizmann Inst. of Science, Rehovoth, Israel 76100; 972-0-89-34-2246; fax 972-0-89-34-4139; e-mail david.cahen@weizmann.ac.il; www.weizmann.ac.il/material/.

6–12 Winter Conf. on Plasma Spectrochemistry, *Scottsdale, AZ.* R. Barnes, ICP Information Newsletter, Inc., P.O. Box 666, Hadley, MA 01003-0666; 413-256-8942; fax 413-256-3746; e-mail winterconf@chem.umass.edu;www.chem.umass.edu/WinterConf2002.

FEBRUARY 2002

17–21 ▼ TMS Annual Meeting, *Seattle, WA.* TMS, 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail weissp@tms.org; www.tms.org/meetings/.

MARCH 2002

2–3 ▼ Conf. on Film Formation: Mechanism, Properties, and Characterization, *Hilton Head, SC.* Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail info@ims-np.org; http://ims-np.org/.

2–3 ▼ Conf. on Polymer Degradation and Stabilization, *Hilton Head, SC.* Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail info@ims-np.org; http://ims-np.org/.

4–6 ▼ 4th Biennial Conf. on Polymer Stabilizers and Modifiers, *Hilton Head, SC.* Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail info@ims-np.org; http://ims-np.org/.

4–6 ▼ Conf. on Film Formation: Science and Technology, *Hilton Head, SC.* Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail info@ims-np.org; http://ims-np.org/.

18–22 ▼ APS March Meeting, *Indianapolis, IN.* American Physical Society, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3200; fax 301-209-0865; e-mail meetings@aps.org; www.aps.org.

18–22 ▼ Intl. Solvent Extraction Conf., *Cape Town, South Africa.* Conf. Secretariat, Private Bag X3015, Randburg 2125, South Africa; 27-11-709-4255; fax 27-11-709-4326; e-mail isec2002@mintek.co.za; www.isec2002.org.za.

APRIL 2002

1–5 ▼ **MRS Spring Meeting**, *San Francisco, CA.* Materials Research Society, 506 Keystone Dr., Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail info@mrs.org; www.mrs.org. **MRS.**

28–1 ▼ 104th ACerS Annual Meeting, *St. Louis, MO.* The American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-890-4700; fax 614-899-6109; e-mail info@acers.org; www.ceramics.org.

JUNE 2002

10–14 ▼ **8th Intl. Conf. on Electronic Materials**, *Xi'an, China.* J. Cheng; 86-10-6894-4280; fax 86-10-6842-8640; e-mail cmrssec@public.bta.net.cn; www.c-mrs.org.cn/icem2002/. **C-MRS.**

16–20 ▼ Intl. Cryogenic Materials Conf., *Xi'an, China.* Y. Feng, Northwest Inst. for Non-ferrous Metal Research, P.O. Box 51, Xi'an, Shaanxi 710016, China; 86-29-623-1079; fax 86-29-623-1103; e-mail smrc@pub.xaonline.com.

23–28 ▼ 11th Intl. Meeting on Lithium Batteries, *Monterey, CA.* IMLB 11 Conf. Secretariat, c/o The Electrochemical Society, Inc., 65 S. Main St., Pennington, NJ 08534-2839; 609-737-1902; fax 609-737-2743; e-mail ecs@electrochem.org; www.electrochem.org/meetings/011/imlb11.html.

JULY 2002

1–5 ▼ Conf. on Coatings Science and Technology, *Athens, Greece.* Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail info@ims-np.org; http://ims-np.org/.

1–5 ▼ Intl. Conf. on Fuel Cells, *Lucerne, Switzerland.* European Fuel Cell Forum, P.O. Box 99, CH-5452 Oberrohrdorf, Switzerland; 41-56-496-7292; fax 41-56-496-4412; e-mail info@efcf.com; www.efcf.com.

29–2 ▼ 26th Intl. Conf. on the Physics of Semiconductors, *Edinburgh, Scotland.* Conf. Dept., ICPS2002, Inst. of Physics, 76 Portland Place, London W1B 1NT, England; 44-20-7470-4800; fax 44-20-7470-4900; www.icps2002.org.

SEPTEMBER 2002

8–12 ▼ 6th Intl. Meeting on Magnetic Resonance in Porous Media, *Ulm, Germany.* www.uni-ulm.de/nmr/mrpm6/early_notification.htm.